TOSHIBA Photocoupler GaAs Ired & Photo-Transistor

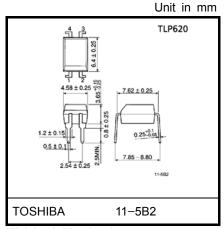
TLP620, TLP620-2, TLP620-4

Programmable Controllers AC / DC-Input Module Telecommunication

The TOSHIBA TLP620, -2 and -4 consists of a photo-transistor optically coupled to two gallium arsenide infrared emitting diode connected in inverse parallel.

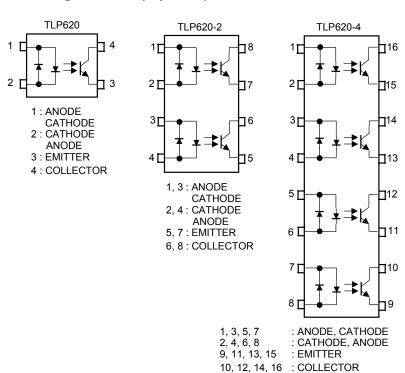
The TLP620–2 offers two isolated channels in an eight lead plastic DIP, while the TLP620–4 provides four isolated channels in a sixteen plastic DIP.

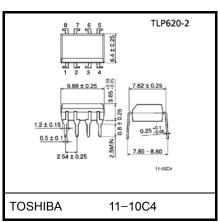
- Collector-emitter voltage: 55V (min.)
- Current transfer ratio: 50% (min.) Rank GB: 100% (min.)



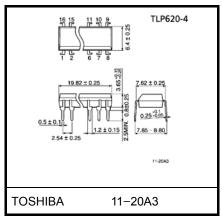
Weight: 0.26 g (typ.)

Pin Configurations (top view)





Weight: 0.54 g (typ.)



Weight: 1.1 g (typ.)

	Made In Japan		Made In Thailand	
UL recognized	E67349	*1	E152349	*1
BSI approved	7426, 7427	*2	7426, 7427	*2

*1 UL1577

*2 BS EN60065: 2002, BS EN60950-1: 2002

• Isolation voltage: 5000V_{rms} (min.)

• Option (D4) type

VDE approved: DIN EN 60747-5-2, certificate no.40009302 Maximum operating insulation voltage: 890VPK Highest permissible over voltage: 8000VPK

(Note) When an EN 60747-5-2 approved type is needed, please designate the "Option(D4)".

• Creepage distance: 6.4mm (min.)

Clearance: 6.4mm (min.)

Insulation thickness: 0.4mm (min.)

Absolute Maximum Ratings (Ta = 25°C)

			Rat	Rating		
	Characteristic	Symbol	TLP620	TLP620–2 TLP620–4	Unit	
	Forward current	I _F (RMS)	60	50	mA	
	Forward current derating	ΔI _F / °C	-0.7 (Ta ≥ 39°C)	–0.5 (Ta ≥ 25°C)	mA / °C	
Ω	Pulse forward current	I _{FP}	1 (100µs pul	lse, 100pps)	А	
LED	Power dissipation (1 circuit)	PD	100	70	mW	
	Power dissipation derating	ΔP _D / °C	-1.0	-0.7	mW / °C	
	Junction temperature	Tj	12	25	°C	
	Collector-emitter voltage	V _{CEO}	5	5	V	
	Emitter-collector voltage	V _{ECO}	7	7	V	
Collector current	Collector current	IC	50		mA	
Detector	Collector power dissipation (1 circuit)	PC	150	100	mW	
	Collector power dissipation derating (1 circuit) (Ta ≥ 25°C)	ΔP _C / °C	-1.5	-1.0	mW / °C	
	Junction temperature	Tj	12	25	°C	
Sto	rage temperature range	T _{stg}	−55 ~	−55~125		
Оре	erating temperature range	T _{opr}	−55 ~	-100	°C	
Lea	d soldering temperature	T _{sold}	260 (260 (10s)		
Tota	al package power dissipation	PT	250	250 150		
	al package power dissipation ating (Ta ≥ 25°C, 1 circuit)	ΔP _T / °C	-2.5	-1.5	mW / °C	
Isol	ation voltage	BVS	5000 (AC, 1 m	in., RH ≤ 60%)	V _{rms}	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).



Recommended Operating Conditions

Characteristic	Symbol	Min.	Тур.	Max.	Unit
Supply voltage	V _{CC}	_	5	24	V
Forward current	I _{F (RMS)}	_	16	20	mA
Collector current	IC	_	1	10	mA
Operating temperature	T _{opr}	-25	_	85	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

Individual Electrical Characteristics (Ta = 25°C)

	Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
	Forward voltage	V _F	I _F = ±10mA	1.0	1.15	1.3	V
LED	Forward current	l _F	V _F = ±0.7V	_	2.5	20	μA
	Capacitance	C _T	V = 0, f = 1MHz	ı	60	-	pF
	Collector–emitter breakdown voltage	V (BR) CEO	I _C = 0.5mA	55	_	_	V
ctor	Emitter-collector breakdown voltage	V (BR) ECO	I _E = 0.1mA	7	_	_	V
Detector	Collector dark current	lana	V _{CE} = 24V	_	10	100	nA
	Collector dark current	ICEO	V _{CE} = 24V, Ta = 85°C		2	50	μA
	Capacitance (collector to emitter)	C _{CE}	V _{CE} = 0, f = 1MHz	_	10	_	pF

Coupled Electrical Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Mln.	Тур.	Max.	Unit
Current transfer ratio	I_C / I_F $I_F = \pm 5 \text{mA}, V_{CE} = 5 \text{V}$ Rank GB	I _F = ±5mA, V _{CE} = 5V	50	_	600	%
Current transfer ratio		100	ı	600	/0	
Saturated CTR	lo / le /	IF = ±1mA, V _{CE} = 0.4V Rank GB	_	60		- %
	I _C / I _F (sat)		30	ı	1	
	VCE (sat)	I _C = 2.4mA, I _F = ±8mA	_	_	0.4	
Collector–emitter saturation voltage		I_C = 0.2 mA, I_F = ±1 mA Rank GB	_	0.2	-	V
			_	_	0.4	
Off-state collector current	I _{C (off)}	$V_F = \pm 0.7V$, $V_{CE} = 24V$	_	1	10	μΑ
CTR symmetry	I _{C (ratio)}	$I_{C} (I_{F} = -5mA) / I_{C} (I_{F} = +5mA)$	0.33	1	3	_



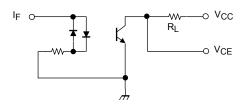
Isolation Characteristics (Ta = 25°C)

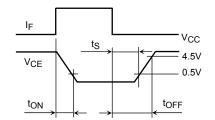
Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Capacitance input to output	CS	V _S = 0, f = 1MHz	_	0.8	_	pF
Isolation resistance	R _S	V _S = 500V	1×10 ¹²	10 ¹⁴	_	Ω
Isolation voltage	BVS	AC, 1 minute	5000	_	_	\/
		AC, 1 second, in oil	_	10000	_	V _{rms}
		DC, 1 minute, in oil	_	10000	_	V _{dc}

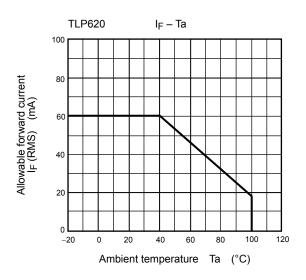
Switching Characteristics (Ta = 25°C)

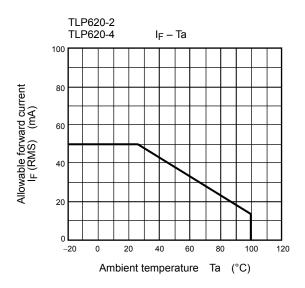
Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Rise time	t _r		_	2	_	
Fall time	t _f	V _{CC} = 10V I _C = 2mA	_	3	_	116
Turn-on time	t _{on}	$R_L = 100\Omega$	_	3	_	μs
Turn-off time	t _{off}		_	3	_	
Turn-on time	t _{ON}		_	2	_	
Storage time	t _S	$R_L = 1.9k\Omega$ (Fig.1) $V_{CC} = 5V, I_F = \pm 16mA$	_	15	_	μs
Turn-off time	tOFF		_	25	_	

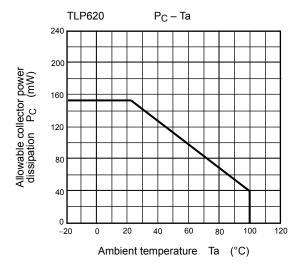
Fig. 1 Switching time test circuit

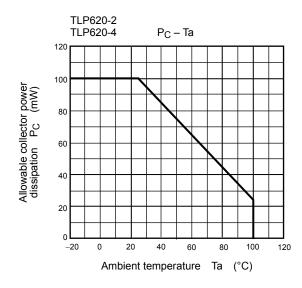


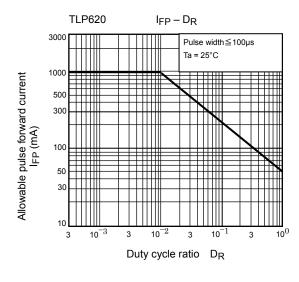


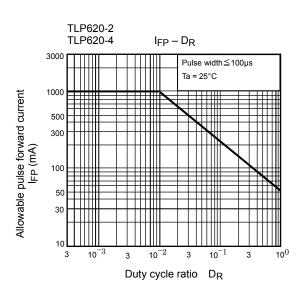




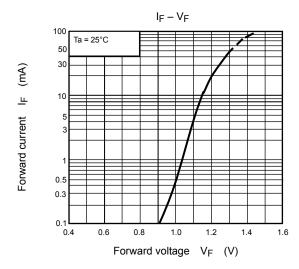


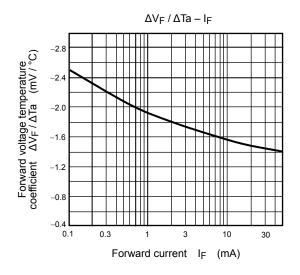


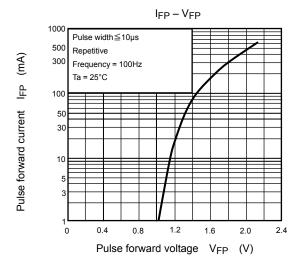


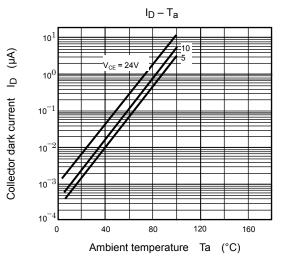


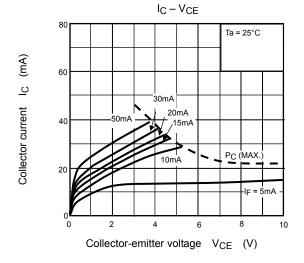
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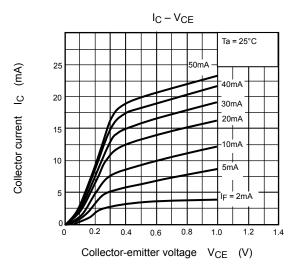




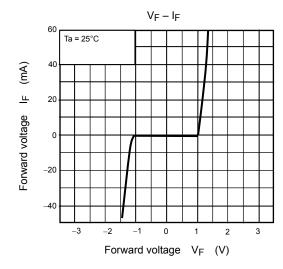


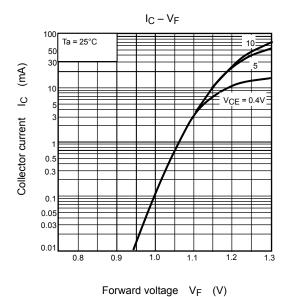


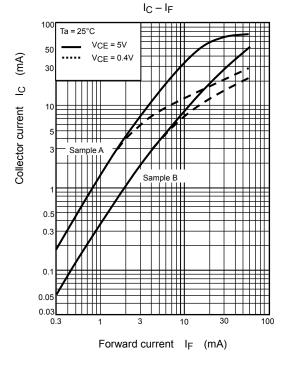


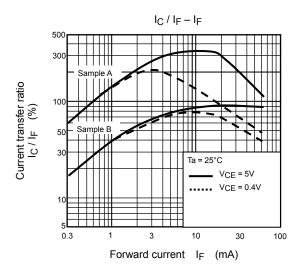


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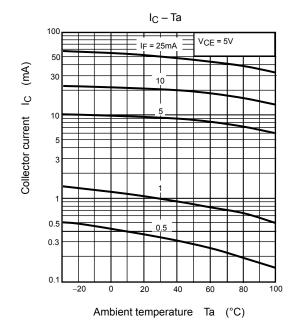


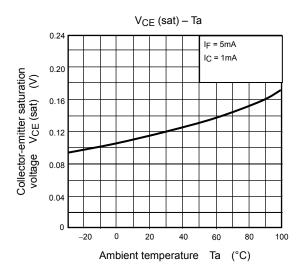


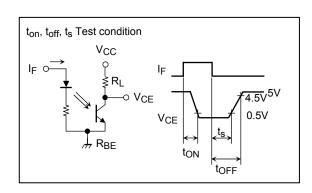


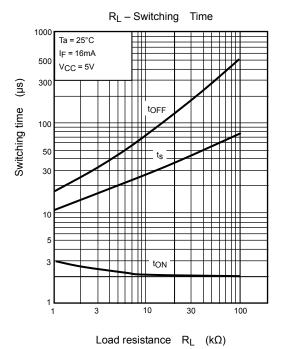


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